

Diodes Inc. Material Data Sheet

Rev: August 2008

Part Number: DDTCxxx-(p)-F

Weight (mg): 8.50 DATE CODE 0833+

p = package designator See Data Sheet XXX= 113TCA, 113ZCA, 114ECA, 114GCA, 114TCA, 114WCA, 114YCA, 115ECA, 115GCA, 115TCA, 123ECA, 123JCA, 123TCA, 123YCA, 124TCA, 124TCA, 124TCA, 124TCA, 124TCA, 143CA, 143XCA, 143ZCA, 144ECA, 144CA, 144TCA, 144TCA, 144WCA, 144WCA

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)			ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.81	0.07	1000000	8052
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.76	2.44	576500	165802
		Ni	7440-02-0	41.00%			410000	117916
		Mn	7439-96-5	0.60%			6000	1726
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	288
		Со	7440-48-4	0.50%			5000	1438
		Si	7440-21-3	0.15%			1500	431
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.22	0.10	1000000	12172
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.19	0.02	1000000	1931
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	66.02	5.61	690000	455516
		Epoxy Resin	29690-82-2	14.00%			140000	92424
		Phenol Resin	9003-35-4	7.00%			70000	46212
		Mg(OH)2	1309-42-8	8.00%			80000	52814
		С	1333-86-4	0.20%			2000	1320
		others		1.80%			18000	11883
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	3.01	0.26	1000000	30076
•				Total	100.00	8.50		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

This product or product family does not contain any of the following substances except as CURRENTLY exempted by ELV II and RoHS and reported above:

Azo compounds

Cadmium and cadmium compounds Certain Shortchain Chlorinated Paraffins

Chlorinated organic compounds Hexavalent chromium compounds Lead and lead compounds

Mercury and mercury compounds

Mercury and mercury comp Organic tin compounds Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)

Perfluorooctane Sulphonate(PFOS) or related compounds

Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) includin **DecaBDE**Polychlorinated Biphenyls (PCBs)

Polychlorinated Naphthalenes (> 3 chlorine atoms)

Radioactive Substances

Tributyl Tin (TBT) and Triphenyl Tin (TPT)

Tributyl Tin Oxide (TBTO)

<sup>\*</sup> The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o EIA JIG-101, <u>Material Composition Declaration for Electronic Products</u>.